



News Release

Unisem Reports Revenue of RM321.6 million (approx. US\$81.9 million) and Net Profit of RM6.3 million (approx. US\$1.6 million) for First Quarter 2018

Kuala Lumpur, 24 April 2018 – Unisem (M) Berhad today announced results for the first quarter ended 31 March 2018 (**1Q18**).

Unisem recorded a consolidated revenue of RM321.551 million (approx. US\$81.9 million) for 1Q18, representing a decline in revenue of 10.7 percent against the corresponding quarter ended 31 March 2017 (**1Q17**). The decrease in revenue was mainly attributable to the depreciation of USD/MYR exchange rate as compared to the prevailing rate in the corresponding quarter a year ago.

For the quarter ended 31 March 2018, the Group recorded net profit of RM6.325 million (approx. US\$1.6 million) as compared to the net profit of RM45.379 million (approx. US\$10.2 million) achieved in 1Q17. The decline in net profit was mainly due to depreciation of USD/MYR exchange rate coupled with lower profit margins arising from change in product mix as well as the recognition of foreign exchange losses of RM9.950 million (approx. US\$2.5 million) in 1Q18.

Group's earnings before interest, tax, depreciation and amortization (EBITDA) for 1Q18 came in at about RM47.651 million (approx. US\$12.1 million), EBITDA margin was about 14.8 percent. Equipment capacity utilization averaged at about 64 percent for the Group in 1Q18. Group's capital expenditure incurred in 1Q18 was about RM45.133 million (approx. US\$11.5 million), principally for purchase of equipment for advanced packaging activities.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, the group managing director said, "We expect the performance of the Group to improve for the second financial quarter and remain satisfactory till the end of the financial year."

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; and in Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com